### *(Green) SOIC Package RELIABILITY QUALIFICATION REPORT SUMMARY*

| Technology Description | Green (Lead and Halide Free) Small Outline Plastic Package in 16, 20 and 28 LD. |
|---|---|
| Qualification Vehicle | SOIC28 |
| | |

| QFN Packaging Information | |
|---|---|
| UL flammability class | UL 94 V-0 & $\geq$ 28% |
| Lead Frame Material | Copper |
| Die Attach | Ablestik 8361J |
| Mold compound | Sumitomo G700LY |
| Bond Wire | Gold |
| Lead Finish | Matte Tin (Sn) |

| Factory Locations | |
|---|---|
| Wafer Fabrication | CSM |
| Assembly | ASE, Malaysia |
| Final Test | ASE, Malaysia |

| Availability | |
|---|---|
| Samples: | Yes |
| Production: | Yes |



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*(Green) SOIC Package RELIABILITY QUALIFICATION SUMMARY*

| Green Package Qualification Stress Tests | #fails/#samples |
|---|---|
| **Preconditioning Jedec Moisture Sensitivity Level 3 with IR reflow at 260 +/- 5°C**<br><br>(Prior to Temperature Cycle and THB 85/85) | **0/300** |
| **Temperature Cycle (-65°C/+150°C, 500 cycles)** | **0/150** |
| **Temperature Humidity Bias (85%R.H., 85°C, 1000 hrs)** | **0/150** |
| **Autoclave (100 %R.H./2 ATM, 121°C, 168 hrs)** | **0/150** |
| **Solderability** | **0/20** |
| **Assembly Yield** | **Equivalent to Standard Material set.** |
| **Construction Analysis** | **Complete / Pass** |

**Qualification Date: January 13, 2005**

**For information on Tin Whiskers, visit the Legerity Green web page at:**
http://www.legerity.com/public.php?p=green

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